



Material Content Data Sheet



Sales Product Name	TLE6251-2G			Issued	26. September 2017			
MA#	MA001465868							
Package	PG-DSO-14-1			Weight*	143.62 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.050	3.52	3.52	35162	35162
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		105	
	non noble metal	zinc	7440-66-6	0.060	0.04		420	
	non noble metal	iron	7439-89-6	1.207	0.84		8404	
wire	non noble metal	copper	7440-50-8	49.007	34.12	35.01	341236	350165
	noble metal	gold	7440-57-5	0.206	0.14	0.14	1436	1436
	encapsulation	organic material	carbon black	1333-86-4	0.168	0.12		1168
	plastics	epoxy resin	-	7.717	5.37		53736	
		inorganic material	silicondioxide	60676-86-0	75.999	52.93	58.42	529179
leadfinish	non noble metal	tin	7440-31-5	1.241	0.86	0.86	8644	8644
plating	noble metal	silver	7440-22-4	1.030	0.72	0.72	7170	7170
glue	plastics	acrylic resin	-	0.421	0.29		2935	
		noble metal	silver	7440-22-4	1.494	1.04	1.33	10405
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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